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www.nanoveu.com

**ASX RELEASE** **10 March 2025**

**ASX: NVU**

# Embedded World 2025 Presentation

*Nanoveu positioned to accelerate growth in AI-driven edge semiconductor solutions*

**Nanoveu Limited** ("Nanoveu" or the "Company") (ASX: NVU), advises of its participation at the embedded world 2025 Conference & Exhibition being held between 11 to 13 March 2025 in Nuremberg, Germany.

The presentation materials are attached for the information of investors and shareholders and can also be accessed, together with an animated version, via the "Presentations" page of the Company's website: www.nanoveu.com/investor-centre/presentations/.

This announcement has been authorised for release by the Board of Directors.

-Ends-

**Further information:**

**Nanoveu Media**
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Managing Director and CEO
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e: info@nanoveu.com

## About Nanoveu Limited

**Further details on the Company can be found at https://nanoveu.com/.**

**EMASS**

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

**EyeFly3D™**

The EyeFly3D™ platform is a comprehensive solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

**Nanoshield™ -** is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include:

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***Nanoshield™ Marine***, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and

***Nanoshield™ Solar***, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

**Forward Looking Statements**

This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

# nanoveu

## An applied technology company

embeddedworld 2025 Presentation
Exhibition&Conference

Animated version of the presentation can be found here

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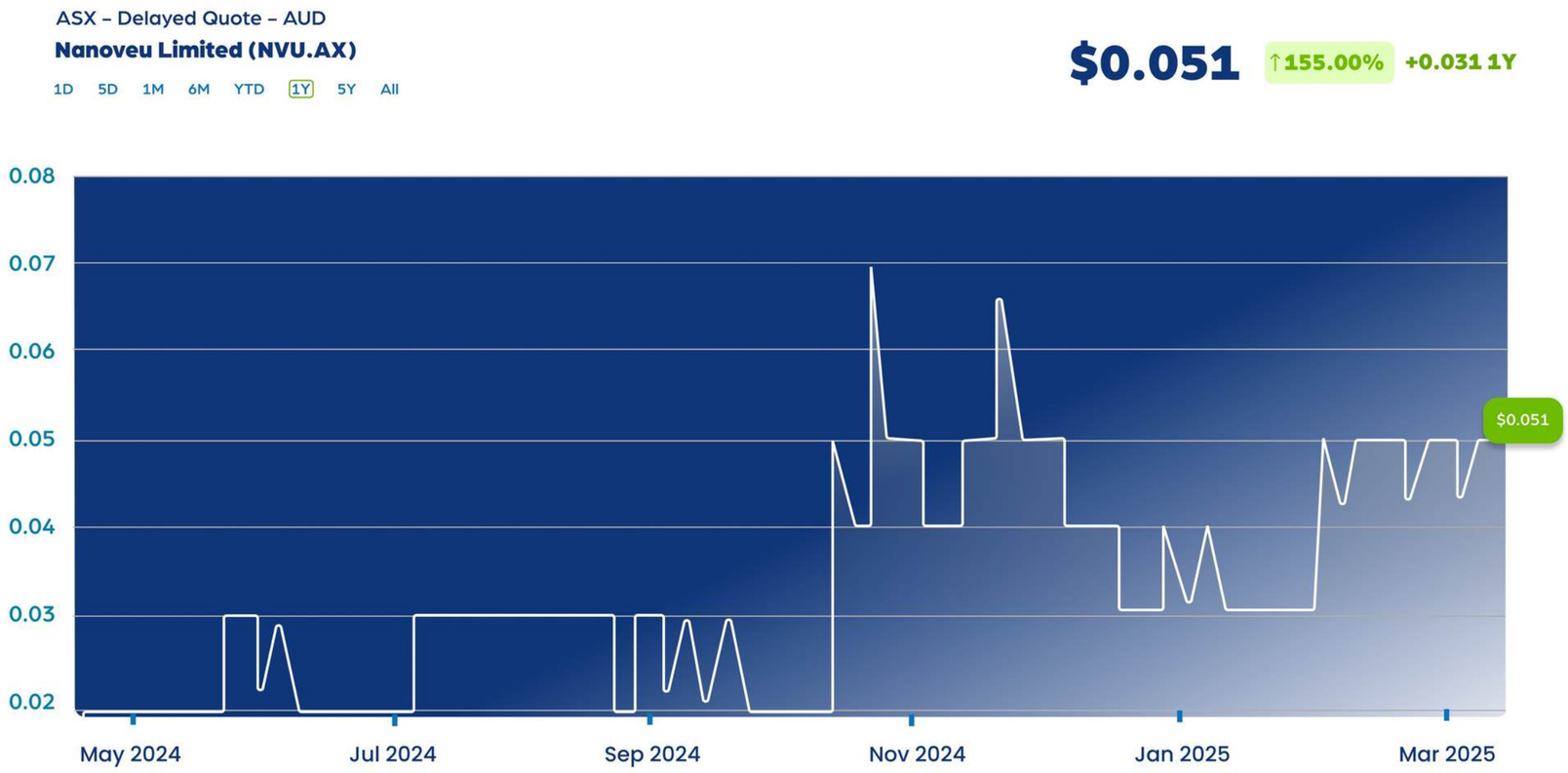
**AUTHORISATION** This document has been authorised for release by the Company's Board of Directors.

# Capital Structure

## Nanoveu Share Price




## Capital Structure*

| | |
|---|---|
| ASX Code | NVU |
| Shares on Issue | 742.4m |
| Options on Issue | 235.3m |
| Performance Rights on Issue | 168.9m |
| Previous Close | $0.051 |
| Average Volume | 3.27m |
| Market Cap | $37.86m |

*Post EMASS acquisition settlement (includes 172.4m shares + 83.3 performance rights)

# Our Board

## DR. DAVID PEVCIC

### Executive Chairman

- Experienced professional and investor in the resources and technology sector.
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8).
- Non-Executive Director at Infant Resources (ASX: 188).
- Holds a Bsc, MBBS, from the university of Western Australia.

## ALFRED CHONG

### Group Chief Executive Officer

- Founder Of Nanoveu, Has 30+ Years Of Experience In Scaling Companies And Trade Sales.
- Former CEO Of: Atex Media Command (APAC) ,THISS Technologies ,121View.
- Former CMO At 3D International.

## STEVE APEDAILE

### Non-Executive Director

- 30 Years Of Experience In Accounting.
- Worked At KPMG And Horwath Hong Kong.
- Fellow Of The ICAEW.
- Member Of The AICD.
- Executive Chairman Of Sprintex (ASX:SIX).

## DR. MICHAEL WINLO

### Non-Executive Director

- Former CEO Of Linear Clinical Research.
- Former Health Lead At Palantir (NYSE:PLTR).
- Holds An MBA From Stanford And An MBBS From UWA.

# Semiconductor Leadership Team

*"We are positioning ourselves to meet growing global demand for low energy but powerful chips driven by the increasing demand for AI-supported applications."*

## Mark Goranson

**CEO of Semiconductor Technology**

### Notable Positions

- Vice President of global operations, TE connectivity (NYSE: TEL).
- Senior Vice President of Fab Operations, ON Semiconductor (NASDAQ: ON).
- Vice President of Fab Operations Freescale Semiconductor (NYSE: FSL).
- Early member of Intel Corporation (NASDAQ: INTC) for 18-years.
- Holds a B.Sc. in Physics/Electronics from New Mexico Tech.

*"EMASS's ultra-low-power semiconductor technology has remarkable potential to transform AI enabled hardware, addressing a critical industry need for more efficient edge computing."*

## Dr. Mohamed M. Aly

**Founder of EMASS**

### Notable Positions

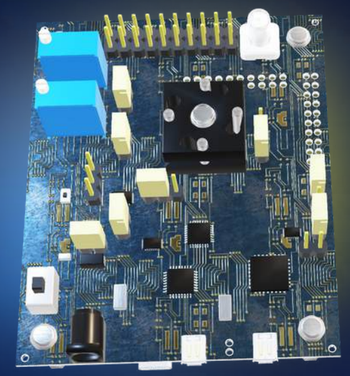
- Associate Professor at NTU Singapore, specializing in AI computing systems.
- Former Postdoc at Stanford (2014–2017).
- Senior IEEE Member.
- Collaborated with Stanford and TSMC.
- Recipient of the Nanyang Education Award (2023).
- Holds a Ph.D. from EPFL.

# Semiconductor And System On Chip (SoC) For AI Computing "On The Edge"

EMASS

EyeFly 3D

NANOSHIELD™

The Backbone of Modern Tech – Semiconductors & SoCs power healthcare, automotive, and smart IoT, making devices faster & more intelligent.

Compact & Energy-Efficient – Low-power, high-performance AI processing, perfect for next-gen connected technology.

# Major Sectors Driving Demand for Energy Efficient AI Infrastructure

## Aerospace And Defense

- Drones and UAVs for navigation, video processing and communication
- Military radar and surveillance

## Consumer Electronics

- Smart Phones and Tablets.
- Wearables and Smartwatches.
- Smart TV and appliances.

## Smart Cities

- Robotics and real time control.
- Predictive maintenance to collect and process sensor data on equipment health.

## Healthcare

- Portable diagnostics equipment's
- Imaging Systems like CT and MRI use SoCs for advanced processing


## Automotive

- Optimized Battery Management.
- Seamless Navigation Systems.
- Enable Safe And Intelligent Driving.

## Energy And Utilities

- Smart Meters for efficient energy resource management
- Optimized solar and wind energy systems

## Gaming & Entertainment

- Used in consoles for graphics and processing.
- VR/AR for immersive experiences.

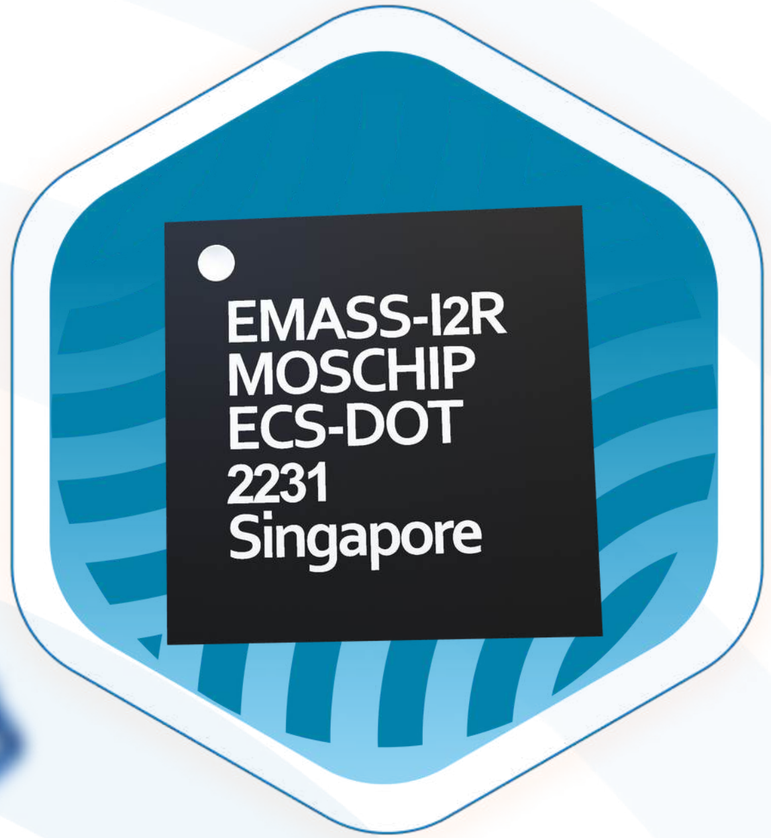
## Data Centers & Cloud Computing

- Unprecedented growth in demand for cloud computing to support AI and ML usage

## Telecommunications

- Networking communications such as Routers and Modems.
- Satellites for space communication.

# The EMASS Opportunity




## 1 An SoC With AI Capabilities

- **Problem** – Increasing demand for computational power that can handle AI workloads on the "edge", faster data processing and analysis
- **Solution** – EMASS's chip is capable of high AI workloads at its low power and form factor

## 2 Ultra Energy Efficient

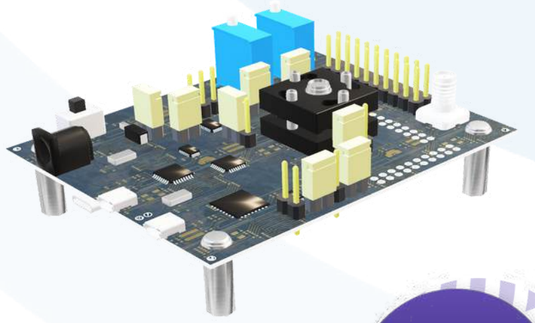
- **Problem** – Current Solutions struggle to run AI computations without high power consumption
- **Solution** – EMASS can run AI models efficiently allowing for a wide range of applications

## 3 High Levels Of Interoperability

- **Problem** – Integrating SoCs into edge devices can be complex
- **Solution** – EMASS's RISC-V architecture is widely accepted with a strong community ensuring seamless integration, and future-proof solutions .

# EMASS Superior Performance, Low Power, Small Form Factor

Leveraging The RISC-V Chip Architecture For Efficiency And Interoperability



Integrated EMASS SoC with AI & Accelerator module

**AI Capacity**

30 Giga-Operations Per second @ 50 MHz, 2mW

**Power Efficiency**

Up to 12 TOPs/Watt

**On-chip dense memory**

4 MBytes

**Hardware support for compressed AI models**

Compressed AI Model < 2-bits

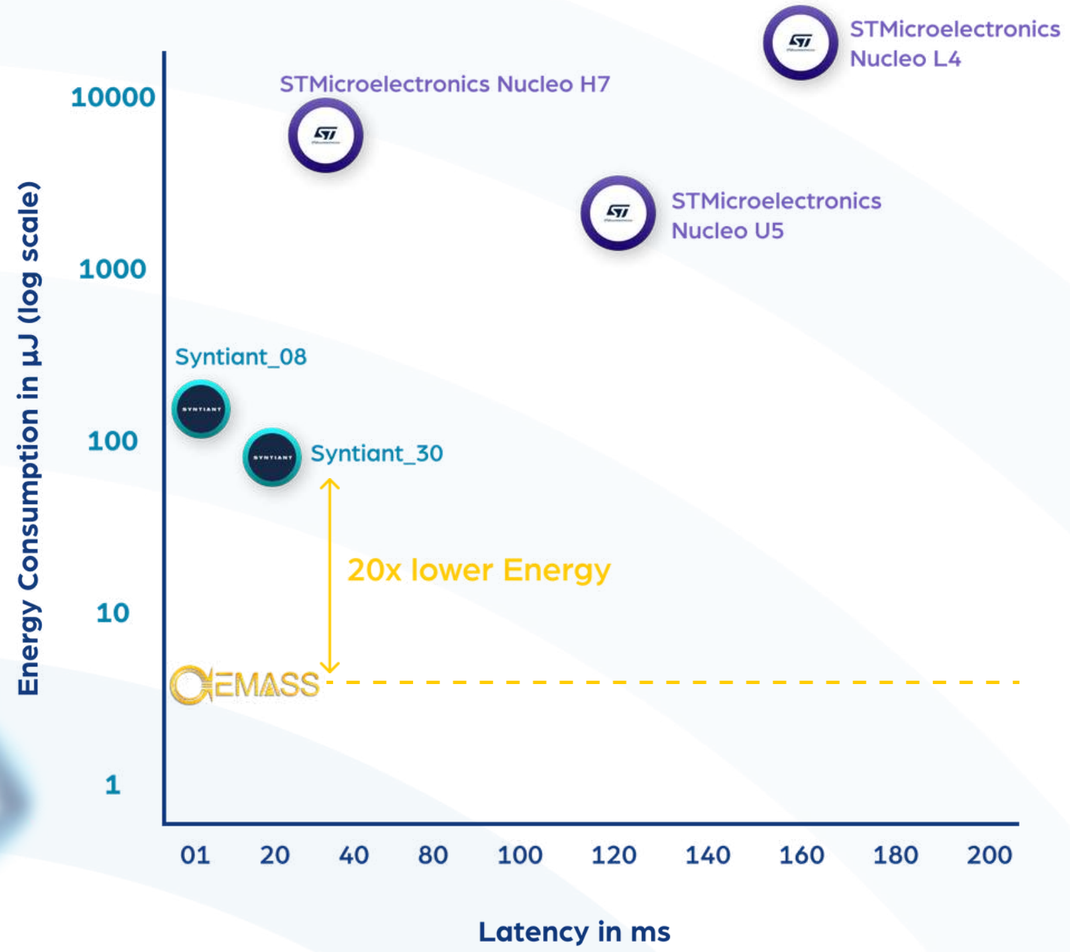
**Physical size**

22nm technology with 7mm$^2$ die area

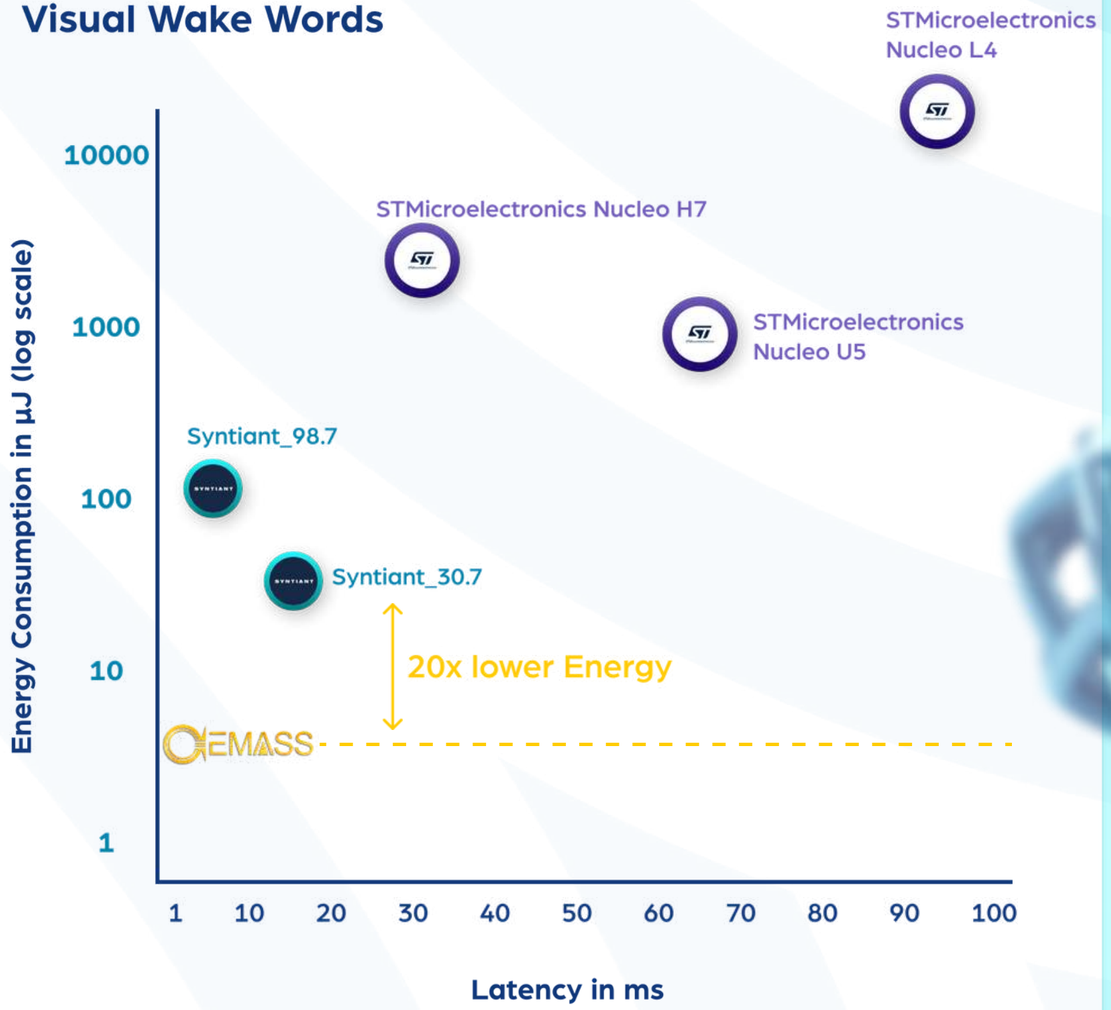
# EMASS Exceptional AI Computation, 20X Lower Energy

EMASS's SOC has greater AI performance compared to today's leading chips

## Image Classification




## Visual Wake Words



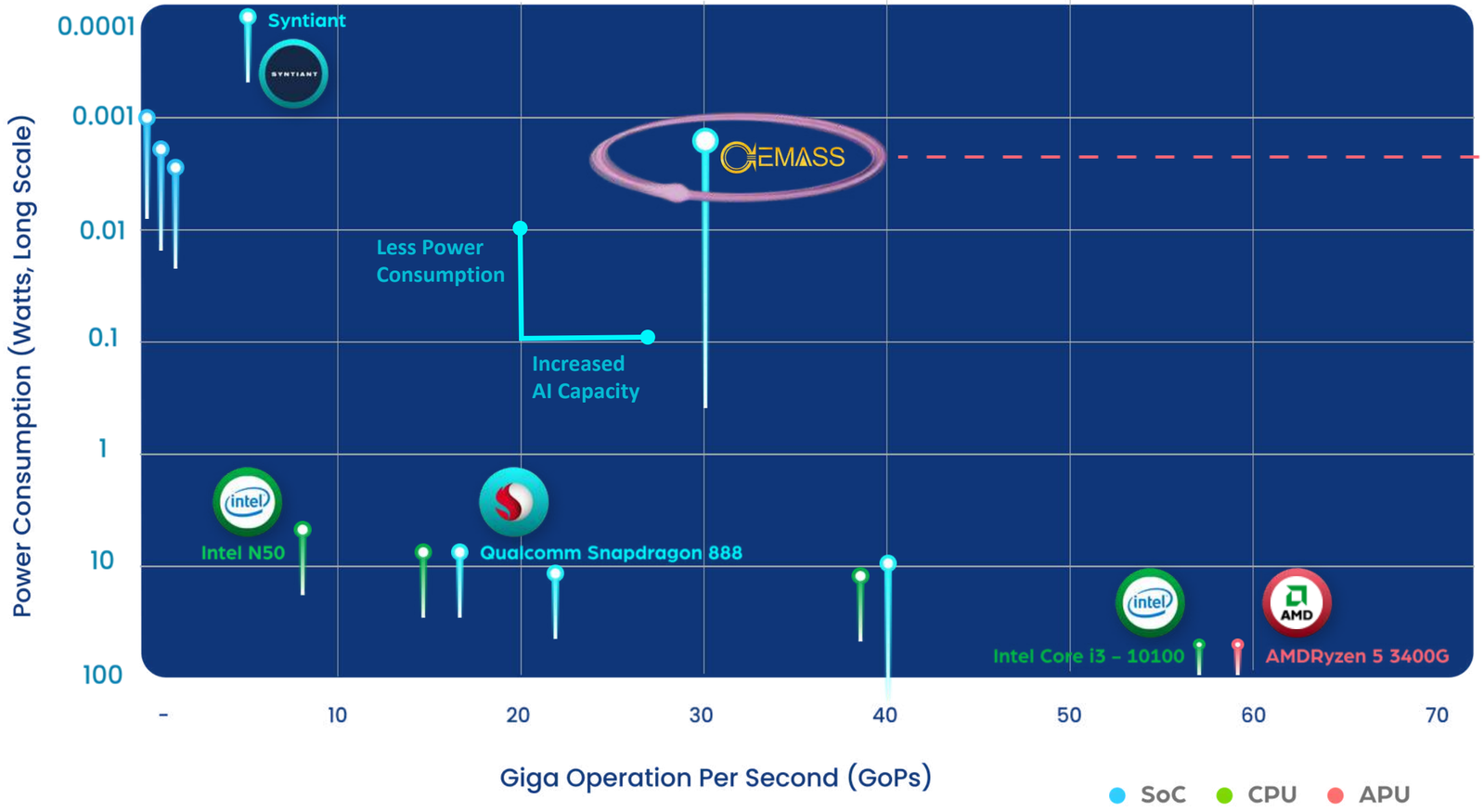
# EMASS Leads Industry Peers In AI Computation Tasks

| Company | Software Optimization | Target Application | AI Performance per Watt (Avg/Peak) | Power (Avg/Peak) | AI Performance | Max AI Parameters |
|---|---|---|---|---|---|---|
| Nanoveu | YES | 3D Vision, Health Monitoring, Wearable, Smart infrastructure | 3/15 ToPs | 0.1mW/10mW | 30 GOPs | 13 million |
| Maxim Integrated | NO | Medical, Patches, Wearable | 1.6/64 GoPs | 50mW/2W | 3.2 GOPs | 3.5 million |
| Himax | NO | Vision, Speech, Gesture, Agriculture, Retail | 40/320 GoPs | 2.5mW/20mW | 0.8 GOPs | 500 K |
| Syntiant | NO | Vision, Smart home, Smartwatches | 0.1/1 ToPs | 7/30mW | 6.4 GOPs | 7 Million |
| Ambiq | NO | Smart home, Smart watches, Fitness trackers, Animal tracker, Voice remote | 240/133 GoPs | 1mW/1.8mW | 0.24 GOPs | 1 Million |
| ETA Compute | NO | Vision | 200 GoPs | 2mW | 0.4 GOPs | 256 K |

*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

# EMASS Delivers Exceptional Energy Efficiency

EMASS's SOC has greater AI performance compared to today's leading chips




## EMASS SoC: Power-Efficient AI For Next-Gen IoT

- Complete AI Capability – EMASS SoC delivers full AI operations with top power efficiency.
- Optimized for IoT – Ideal for battery-sensitive devices without performance loss or extra power drain.
- Seamless Integration – No hardware modifications required, enabling next-gen IoT development.

# EMASS Has Leading Energy Efficiency Compared To Peers

EMASS nanoveu

## Selected Chip Performances

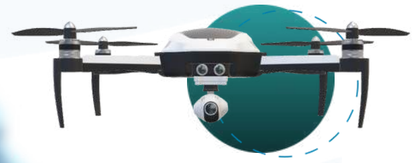
| Company | Chip | Chip Type | Target Industry | Max Performance per Watt | Power Consumption(TBP) | Max Perfomance |
|---|---|---|---|---|---|---|
| NANOVEU | EMASS | SOC | IoT, Wearables, Drones Artificial Intelligence | 3–15 TOPS | 0.1 – 10 MilliWatts | ~30 GoPs |
| AMD | Ryzen 5 3400G | APU | Computing | ~0.91 TOPS | 65 Watts | ~59 ToPs |
| INTEL | Processor N50 | CPU | IoT, Chromebook | ~0.53 TOPS | 75 Watts | ~40 ToPs |
| ARM | Cortex-A53 | CPU | Smartphone, Tablets, Wearables, IoT | ~0.0019 TOPS | 7.5 Watts | ~14 GoPs |
| QUALCOMM | Snapdragon 888 | SOC | Artificial Intelligence, Wearables, Smartphone | ~2.1 TOPS | 8 Watts | ~17 ToPs |
| BROADCOM | BCM2712 | CPU | Robotics, industrial automation, edge computing | ~3.2 TOPS | 12 Watts | ~38 ToPs |
| MEDIATECH | Helio P60 | SOC | Artificial Intelligence Processing, Smartphones | ~4 TOPS | 10 Watts | ~40 ToPs |
| MARVELL | Octeon TX2 | SOC | 5G Networks & Data Centres | ~0.67 TOPS | 30 Watts | ~20 ToPs |

*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

# EMASS Expands Market Opportunities for Nanoveu


## Smartwatch

- Live Biometric Processing – Non-invasive oxygen, hydration, and blood glucose analysis.
- Predictive Diagnosis – Early disease detection.

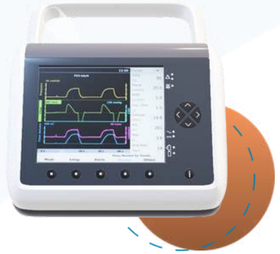


## Drones

- AI Self-Navigating Drones – For crop and livestock monitoring.
- Predictive Harvesting – Using multi-spectral and hyper-spectral data


## EMASS SoC Integration

Embeds AI in devices with low power and no hardware upgrades.



## Medical Devices

- 2D to 3D Models – Instant scans and integrated medical imaging.
- Real-Time Diagnostics – For pacemakers and cochlear implants.

## Glasses & Lens

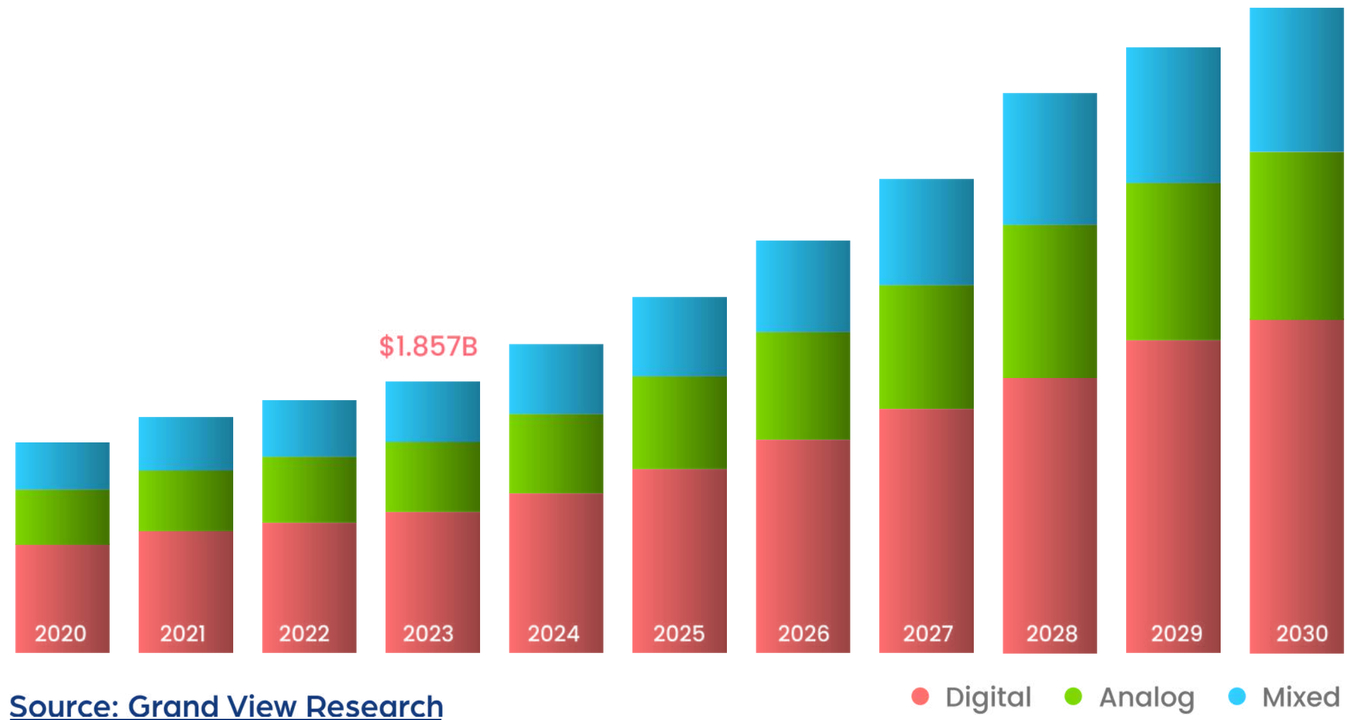
- 2D to Augmented 3D – Virtual FaceTime and calls.
- Immersive AI Assistant – Enhanced experiences

# Semiconductor & SoC Market Set For Rapid Growth

## Powering The Future Of AI & Devices

### System On Chip Market Size

By Type 2020–2030 (USD Billion)




Source: Grand View Research

### SOC Powering The Future Of AI & Devices:

Essential for Next-Gen Tech – SoCs power AI, IoT, and autonomous systems with compact, high-performance computing.

Set to hit

**$325.7B by 2030**

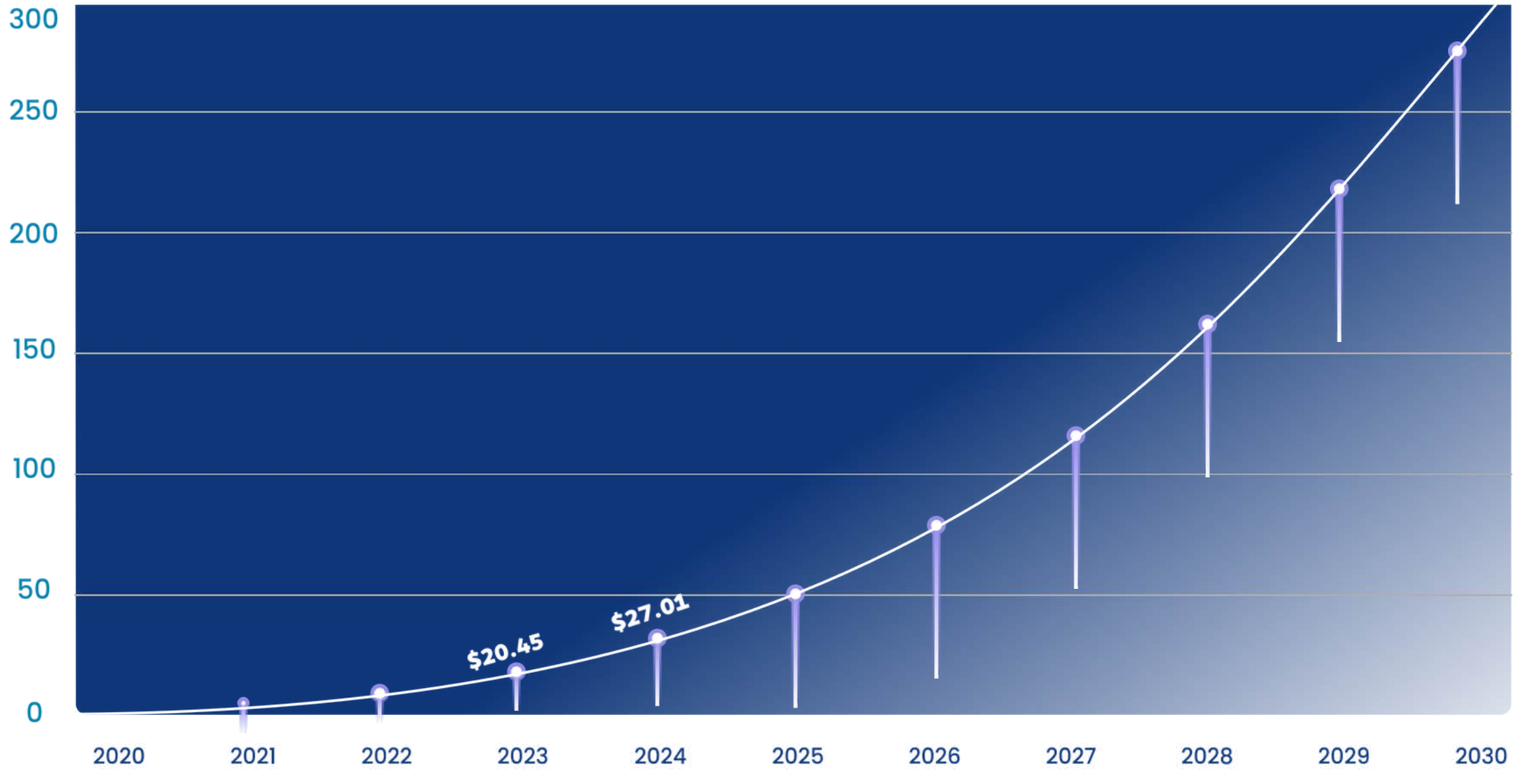
**8.5% Global Market CAGR**

Driven by AI, 5G, and smart devices.

# Poised For Exponential Growth

## Edge AI Smart And Efficient Computing For IOT

### Edge AI  Growth Rate




Source: Fortune Business Insights

### Edge AI: Smart & Efficient Computing For IoT

Faster, Smarter AI – Powers real-time decisions for IoT, autonomous vehicles, and next-gen tech.

Expected To Reach

**$269.82B by 2030**

**33.3% CAGR**

As AI moves to on-device processing.

# Global Development and Collaboration Partners

EMASS has been developed with the world's leading Chip manufacturers and partners

NTUitive Pte Ltd

NANYANG TECHNOLOGICAL UNIVERSITY SINGAPORE

Agency for Science, Technology and Research SINGAPORE

**Early Backers, IP & Development**

Weebitnano THE NEXT NVM IS HERE

**ReRAM Collaboration Partner**

tsmc

MOSCHIP

**IC Fabrication, PCB Fabrication, Packaging**

# Fully Integrated Glasses Free 3D Experiences On Your Mobile Phone

CEMASS

EyeFly3D™

NANOSHIELD™


**EyeFly3D App And AI Algorithm (Software)**

**EyeFly3D Screen Cover (Hardware)**

# EyeFly 3D Delivers Remarkable Glasses–free 3D To Smart Phones and Digital Displays


## Opportunity:

EyeFly 3D dramatically improves the engaging qualities of mobile content. It brings visual content to life allowing users to experience more immersive videos and pictures.

## Key Problem:

There is an increasing opportunity to create more immersive content consumption in a sleek and easy–to–use form factor exemplified by the difficulty in traction within the VR space

## Instant 3D Without Glasses

Converts standard 2D content into stunning 3D, no eyewear required.

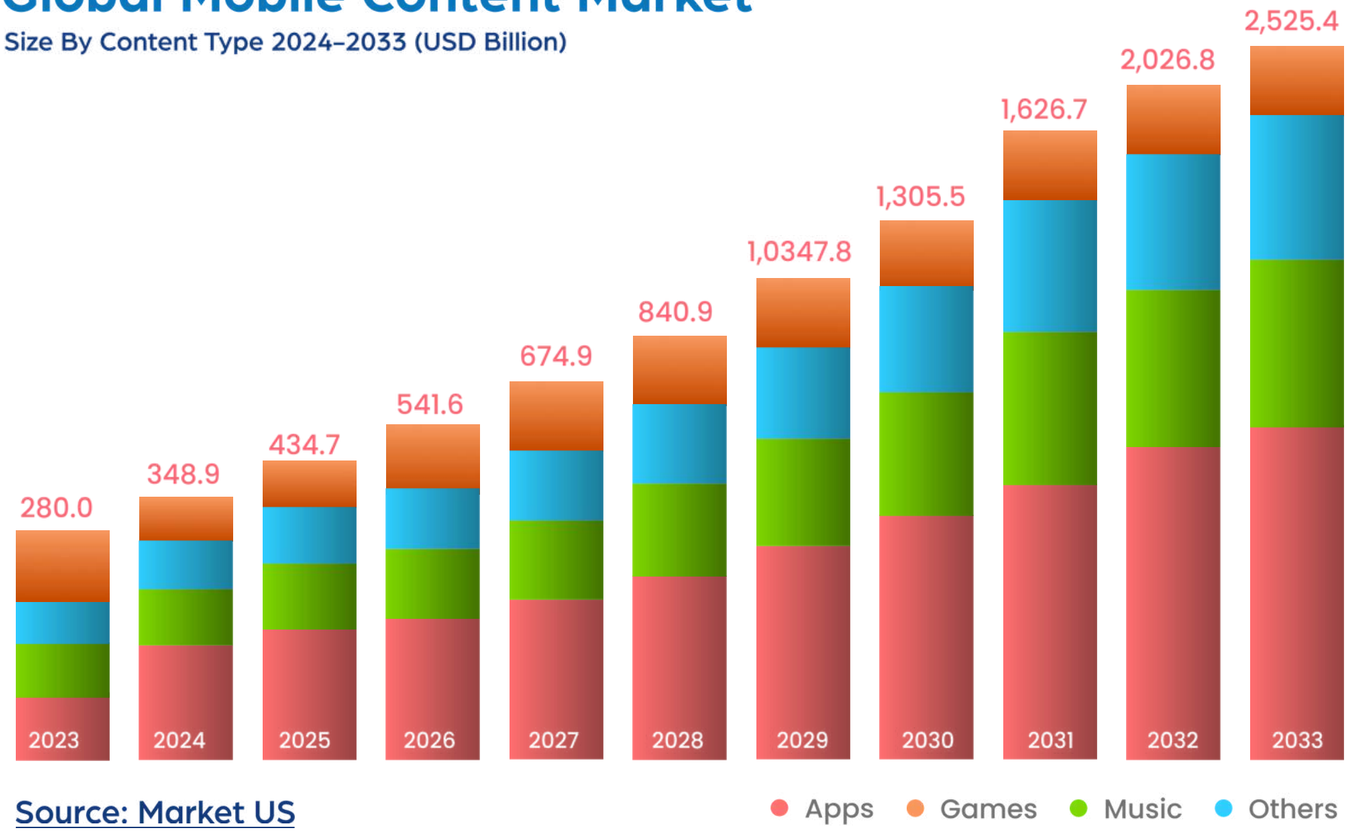
## Communication

EyeFly 3D paving the way for 3D video calls, revolutionizing communication.

# EyeFly 3D Can Impact Some Of The Fastest Growing Segments In Mobile

## Global Mobile Content Market

Size By Content Type 2024–2033 (USD Billion)




Source: Market US

## EyeFly 3D Engagement

Enhances mobile experiences with glasses-free 3D content for richer interactions.

Set to hit

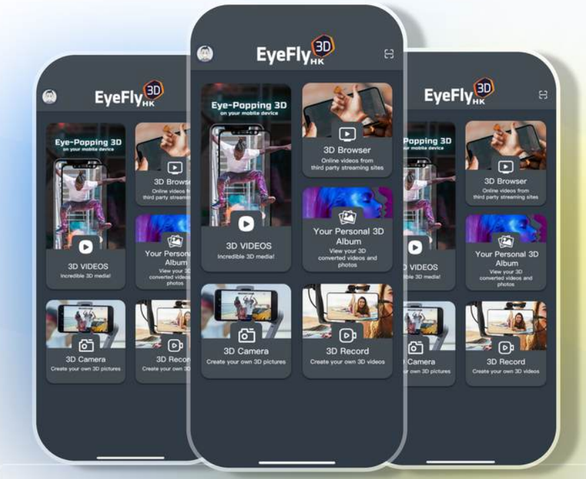
**$2.52T by 2033**

**24.6%CAGR**

Driven by Mobile Apps and Digital Content

# EyeFly3D How Does It Work?

## EyeFly3D Is An Invisible Screen That Brings Your Content To Life




### EyeFly3D App & AI Algorithm (Software)

- Proprietary Software – Converts Images And Videos From 2D To 3D
- Dynamic 3D Mapping – Adjusts Content Based On Screen Distance
- Social App – View And Share 3D Content

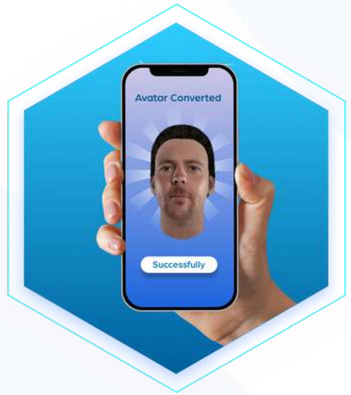
### EyeFly3D Screen Cover (Hardware)

- Patented Nanotechnology – Superior 3D Experience
- Easy Apply Kit – Simple And Hassle-Free
- Brighter & Sharper – Outperforms Competitors

# Launching Soon EyeFly3D App: Allowing users to Create and Share Engaging Glasses–Free 3D Content

## Capture with Ease

Record 3D videos and photos using your phone or the EyeFly3D app.




## Instant 3D Conversion

AI-powered 2D to 3D transformation in seconds.

## Seamless Sharing

Share 3D videos and photos effortlessly.

### Upcoming Features

- Advertising
- Streaming & Content
- Video calling
- Gaming
- 3D communities

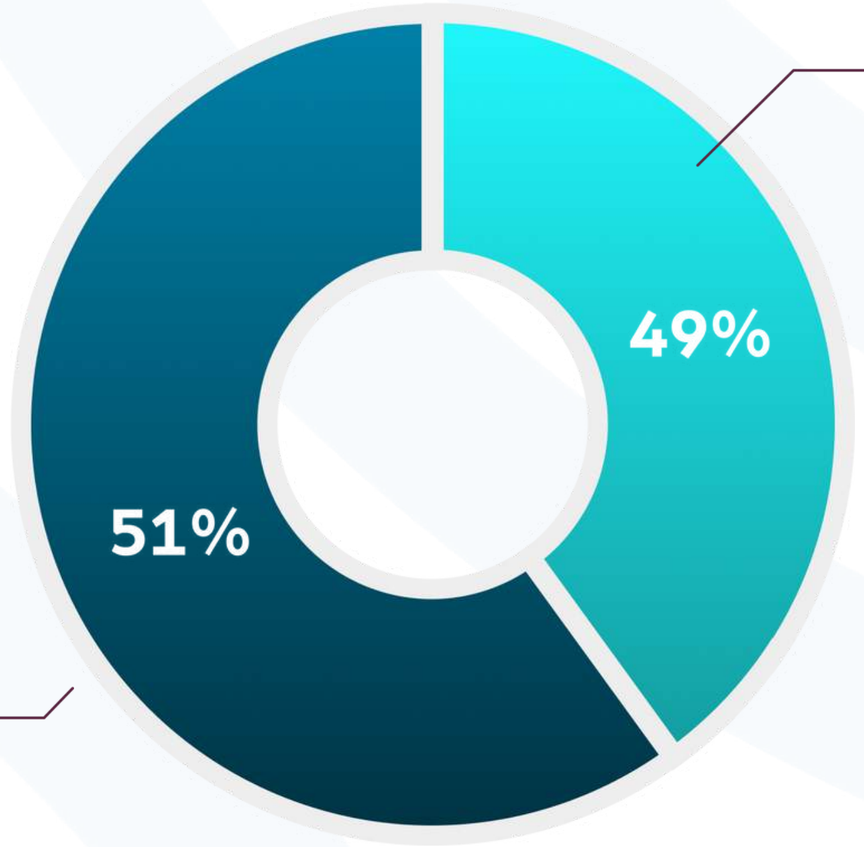
# International Distribution & Expansion Underway

## Key JV Terms:

- Global rights to technology development and distribution (except China).
- Nanoveu gains control over manufacturing, ensuring security and scalability.
- The JV speeds up the development and launch of new technologies worldwide.

## Korean Partners: Rahum Nano Tech, Inc.

- Exclusive distributor of EyeFly3D in Korea. [1]
- Key focus on iPhone 16 Series and the latest Samsung Galaxy S Series.
- Seeking to expand markets for tablets and large format displays.

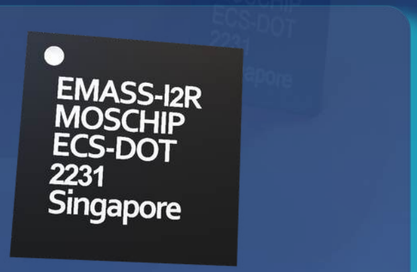



[1] https://wcsecure.weblink.com.au/pdf/NVU/02812220.pdf

# Nanoveu's planned integration of: EMASS x EyeFly3D
# To bring glasses–free 3D to more devices

## Identification of Target Devices: 01

EMASS's energy–efficient SoCs power EyeFly3D for smooth, high–quality 3D on portable devices without draining battery.




## Integration of Chip 02

EMASS will develop the chip for the target smart device enabling more engaging content on tablets, TVs etc.


## Enhanced 3D Experiences 03

EMASS SoCs speed up 2D to 3D conversion, allowing EyeFly3D to render content instantly on any screen without cloud delays.

nanoveu

# Thank You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